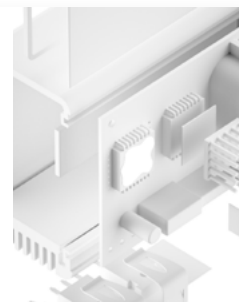


SILICONE-FREE GAP-FILLER/PUTTY TGL-U-NS HALA

dispensable

TGL-U-NS is an electrically insulating thermally conductive, highly viscous dispensable silicone-free form-in-place gap filler. It is ideal for use in applications where thermal transfer over large gaps caused e.g. by big tolerances or different stack up heights must be achieved. The ready-made compound does not require an additional crosslinking process. Due to the specific formulation and filling with ceramic particles the material has a very high thermal conductivity. After dispensing the viscoplastic material leads to an optimum thermal contact at no pressure. By its use the total thermal resistance is minimised.



Release 10 / 2024

PROPERTIESEN

- ☐ Dispensable
- ☐ Almost zero pressure at assembly due to viscoplasticity
- ☐ Thermal conductivity: 4.0 W/mK
- ☐ Ready-made, no additional crosslinking required

AVAILABILITY

- ☐ Cartridge 330 ml
- ☐ Others on request

APPLICATION EXAMPLES

Thermal link of:

- ☐ SMD packages
 - ☐ Through-hole vias
 - ☐ RDRAMs memory modules
 - ☐ Flip Chips, DSPs, BGAs, PPGAs
- For use in Automotive applications / Laptops
/ Medicine engineering / Industrial PCs /
5G Telecommunication equipment

Technical Data Sheet

PROPERTY	UNIT	TGL-U-NS
MATERIAL		
Colour		Ceramic filled silicone-free compound White
Density	g/cm ³	2.9
Viscosity (at 0,5 1/s) (at 1,0 1/s)	Pas	3,300 2,500
Shelf Life (unopened, dry storage conditions at 5–30°C)	Months	6
UL Flammability (Equivalent)	UL 94	V0
RoHS Conformity	2015 / 863 / EU	Yes
THERMAL		
Thermal Conductivity ¹	W/mK	4.0
Operating Temperature Range	°C	– 40 to + 125
ELECTRICAL		
Dielectric Strength	kV / mm	8
Volume Resistance	Ohm - cm	1.0 x 10 ⁹
Dielectric Constant	@ 500 MHz / @ 1 GHz	8.98 / 8.88

Measurement technique according to: ¹ASTM D 5470. All data without warranty and subject to change. Please contact us for further data and information.

All technical data and information are without warranty and believed to be reliable and accurate, corresponding to the latest state of the art. Since the products are not provided to conform with mutually agreed specifications and their use and processing are unknown we cannot guarantee results, freedom from patent infringement, or their suitability for any application. Product testing by the applicant is recommended. We reserve the right of changes.